

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1022	bumpless bump adj less	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:14
L2	95135	(bond\$4 connect\$4) adj2 pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:15
L3	101	embedded near 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:15
L4	195	embedded near2 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:15
L5	1215	1 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:15
L6	393209	(heatsink ((heat thermal\$2) near (sink\$4 spread\$3 dissipat\$3 conducting conductive radiat\$4)) (cool\$3 adj (device apparatus)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:16
L7	1640629	(((printed adj circuit PC wiring) adj (board card module)) pcb PWB motherboard mother adj board) carrier	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:31
L8	5	5 same 6 same 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:19
L9	139	5.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:18
L10	51948	6.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:18

L11	274745	7.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:19
L12	123	1.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:19
L13	17	4.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:19
L14	1	12 with 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:19
L15	1	12 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:19
L16	2264676	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:24
L17	1156138	(micron "mu.m" mu mil)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:24
L18	2363579	thick\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:24
L19	34070	16 near3 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:25
L20	1216376	mm milimeter	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:25

L21	1925263	17 20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:26
L22	4045	19 near3 21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:26
L23	52	22 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:31
L24	126	1 near3 16	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:26
L25	33	22 and 24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:26
L26	2998347	6 lid cap cover	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:31
L27	48	23 and 26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:31
L28	37	27 and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/26 15:31